

Electronic Patent Application Fee Transmittal

Application Number:	10632552			
Filing Date:	02-Aug-2003			
Title of Invention:	Semiconductor multi-package module having package stacked over die-up flip chip ball grid array package and having wire bond interconnect between stacked packages			
First Named Inventor/Applicant Name:	Marcos Carnezos			
Filer:	Bill Kennedy/Paula Hurley			
Attorney Docket Number:	CPAC 1017-5			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180